



QUALIFICATION PLAN SUMMARY

PCN #: BLAS-09IYLA056

**Date:
February 18, 2026**

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for MIC3203-1YM, MAQ3203YM-TRVAO, MAQ3203YM-VAO, MIC3203-1YM-TR, MIC3203YM and MIC3203YM-TR catalog part numbers (CPN) available in 8L SOIC (.150in) package assembled at MTAI site. This is a Q006 Grade 1 qualification.

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for MIC3203-1YM, MAQ3203YM-TRVAO, MAQ3203YM-VAO, MIC3203-1YM-TR, MIC3203YM and MIC3203YM-TR catalog part numbers (CPN) available in 8L SOIC (.150in) package assembled at MTAI site. This is a Q006 Grade 1 qualification.

CCB #: 8038

Misc.	Assembly site	MTAI
	BD Number	BD-003748A
	MP Code (MPC)	2A6164C2XVA1 2A616YC2XVA1
	Part Number (CPN)	MAQ3203YM-VAO MAQ3203YM-TRVAO
	MSL information	MSL1
	Assembly Shipping Media (T/R, Tube/Tray)	Tube, T/R
	Base Quantity Multiple (BQM)	100, 2500
	Reliability Site	MTAI
Lead-Frame	Paddle size	90x90 mils
	Material	CDA194
	DAP Surface Prep	Bare Cu
	Treatment	Roughened
	Process	Stamped
	Lead-lock <i>(Locking Hole, Half Etched, Dimple, etc. If none, please put No or N/A)</i>	Yes
	Part Number	10100841
	Lead Plating	Matte Tin
Strip Density	320 units/strip	
Bond Wire	Material	CuPdAu
Die Attach	Part Number	QMI519
	Conductive	Yes
MC	Part Number	G600V
PKG	Package Type	SOIC
	Pin/Ball Count	8
	PKG width/size	150 mils

Test Name	Conditions	Reliability Stress Read Point Grade 1: -40°C to +125°C (MCHP E Temp)	Pre & Post Reliability Stress Test Temperature Grade 1: -40°C to +125°C (MCHP E Temp)	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011			5	0	1	5		5	30 bonds from a min. 5 devices.
Wire Bond Stich Pull - Wbsp				5	0	1	5		5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001			5	0	1	5		5	30 bonds from a min. 5 devices.
External Visual	Mil. Std. 883-2009/2010			All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	JESD22-A103 +175°C	Grade 1: 500 hrs (+175°C)	Grade 1: +25°C, +125°C	45	5	3	150	0	21 - 167	Perform per the requirements in AEC-Q100/Q101. Spares should be properly identified.
Preconditioning - Required for surface mount devices	J-STD-020 JESD22-A113 +150°C Bake for 24 hours, moisture loading requirements per MSL level 1 + 3X reflow at peak reflow temperature 260°C per Jedec-STD-020E for package type.		Grade 1: +25°C, +125°C	231	15	3	738	0	15	Spares should be properly identified.
HAST	JESD22-A101 or A110 +130°C/85% RH for 96 hrs	Grade 1: 96 hrs (+130°C/85% RH)	Grade 1: +25°C, +125°C	77	5	3	246	0	10 - 22	Perform per the requirements in AEC-Q006. Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
uHAST	JESD22-A102, A118, or A101 +130°C/85% RH for 96 hrs	Grade 1: 96 hrs (+130°C/85% RH)	Grade 1: +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104 -55°C to +150°C	Grade 1: 1000 cycles (-55°C to +150°C)	Grade 1: +25°C, +125°C	77	5	3	246	0	15 - 120	Perform per the requirements in AEC-Q006. Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
HTOL	JESD22-A108 Ta = 125°C	Grade 1: 1000 hrs (Ta = +125°C)	Grade 1: +25°C, -40°C, +125°C test in this sequence	77	5	1	82	0	15 - 60	